Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO252 (DPAK) plastic package intended for use in applications requiring high thermal cycling performance and high junction temperature capability ($T_{i(max)} = 150$ °C).

2. Features and benefits

- High junction operating temperature capability
- High thermal cycling performance
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- · High bidirectional blocking voltage capability
- Surface mountable package
- Very high current surge capability

3. Applications

- Ignition circuits
- Motor control
- Protection circuits e.g. SMPS inrush current
- Voltage regulation
- Crowbar protection

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DRM}	repetitive peak off- state voltage		-	-	600	V
V_{RRM}	repetitive peak reverse voltage		-	-	600	V
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	-	-	180	А
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	_	-	198	Α
T _j	junction temperature		-	-	150	°C
$I_{T(AV)}$	average on-state current	half sine wave; T _{mb} ≤ 133 °C; <u>Fig. 1</u>	_	-	10.2	Α
I _{T(RMS)}	RMS on-state current	half sine wave; $T_{mb} \le 133 \text{ °C}$; Fig. 2; Fig. 3	-	-	16	Α

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Static characte	Static characteristics							
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$		1.5	-	6	mA	
Dynamic chara	Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		300	-	-	V/µs	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	mb	A -
2	Α	anode		G sym037
3	G	gate		symosi
mb	mb	mounting base; connected to anode	DPAK (TO252N)	

6. Ordering information

Table 3. Ordering information

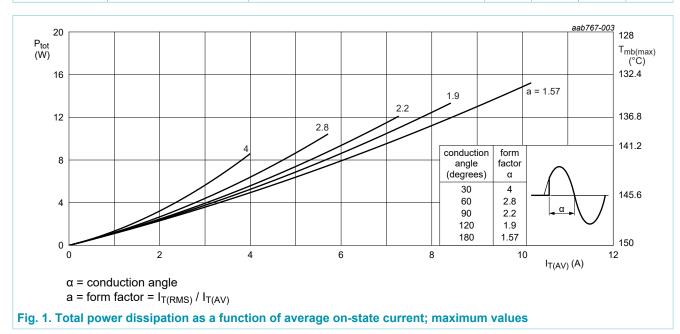
Type number	Package				
	Name	Description	Version		
TYN16S-600CT	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	TO252N		

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	600	V
V_{RRM}	repetitive peak reverse voltage		-	600	V
I _{T(AV)}	average on-state current	half sine wave; T _{mb} ≤ 133 °C; <u>Fig. 1</u>	-	10.2	Α
I _{T(RMS)}	RMS on-state current	half sine wave; $T_{mb} \le 133 ^{\circ}\text{C}$; Fig. 2; Fig. 3	-	16	Α
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4; Fig. 5	-	180	Α
		half sine wave; T _{j(init)} = 25 °C; t _p = 8.3 ms	-	198	Α
I ² t	I ² t for fusing	t _p = 10 ms; SIN	-	162	A²s
dl _T /dt	rate of rise of on-state current	I _G = 30 mA	-	50	A/µs
I _{GM}	peak gate current		-	4	Α
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	10	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	1	W
T _{stg}	storage temperature		-40	150	°C
Tj	junction temperature		-	150	°C



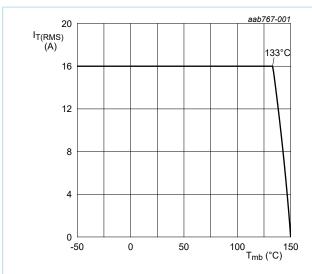


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values

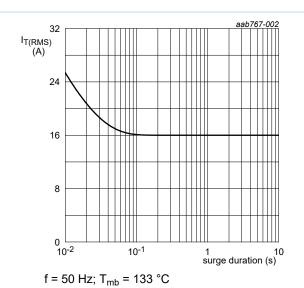


Fig. 3. RMS on-state current as a function of surge duration; maximum values

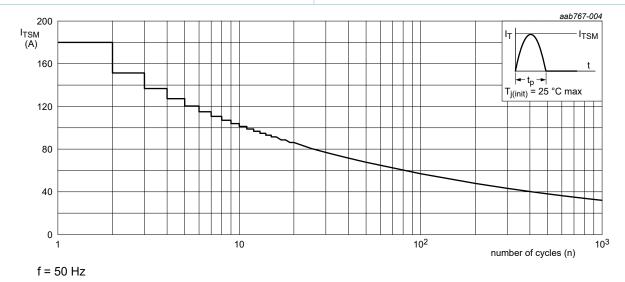
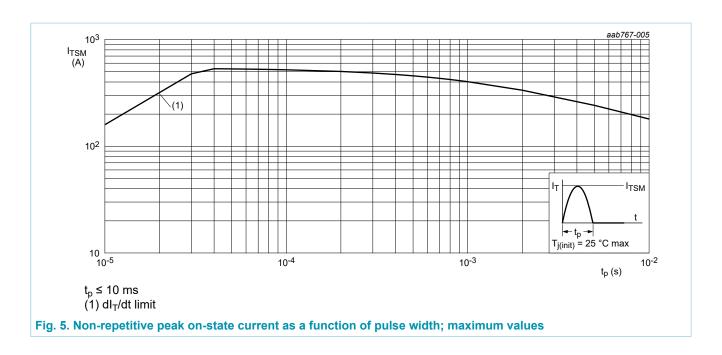


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	<u>Fig. 6</u>	-	-	1.1	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	mounted on a minimum footprint FR4 board	-	55	-	K/W

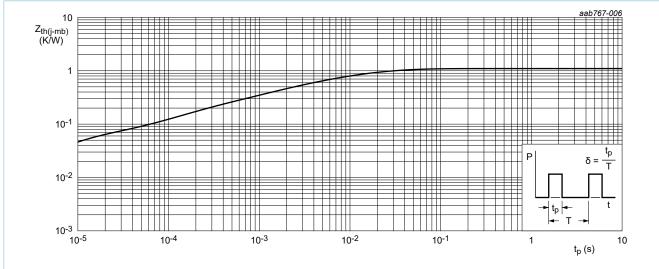


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics		'			
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$	1.5	-	6	mA
IL	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_j = 25 ^{\circ}\text{C}; Fig. 8$	-	-	60	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	40	mA
V_{T}	on-state voltage	I _T = 32 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.2	1.6	V
V _{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11	-	0.7	1.3	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.2	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 150 °C	-	-	1	mA
I _R	reverse current	V _R = 600 V; T _j = 150 °C	-	-	1	mA
Dynamic ch	naracteristics		'	'		
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	300	-	-	V/µs
		V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	100	-	-	V/µs

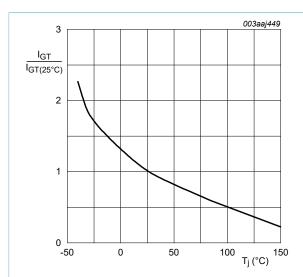


Fig. 7. Normalized gate trigger current as a function of junction temperature

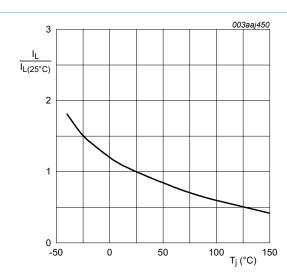


Fig. 8. Normalized latching current as a function of junction temperature

7 / 12

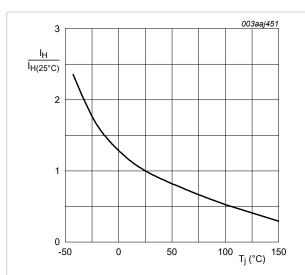
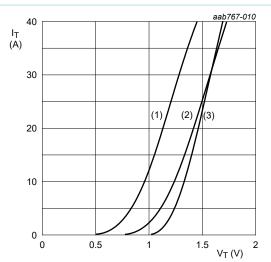


Fig. 9. Normalized holding current as a function of junction temperature



 V_{o} = 1.071 V; R_{s} = 0.0169 Ω

(1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values

(3) $T_j = 25$ °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

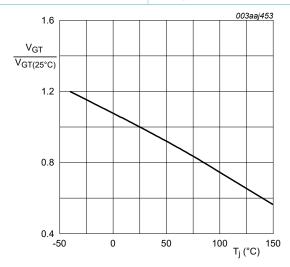
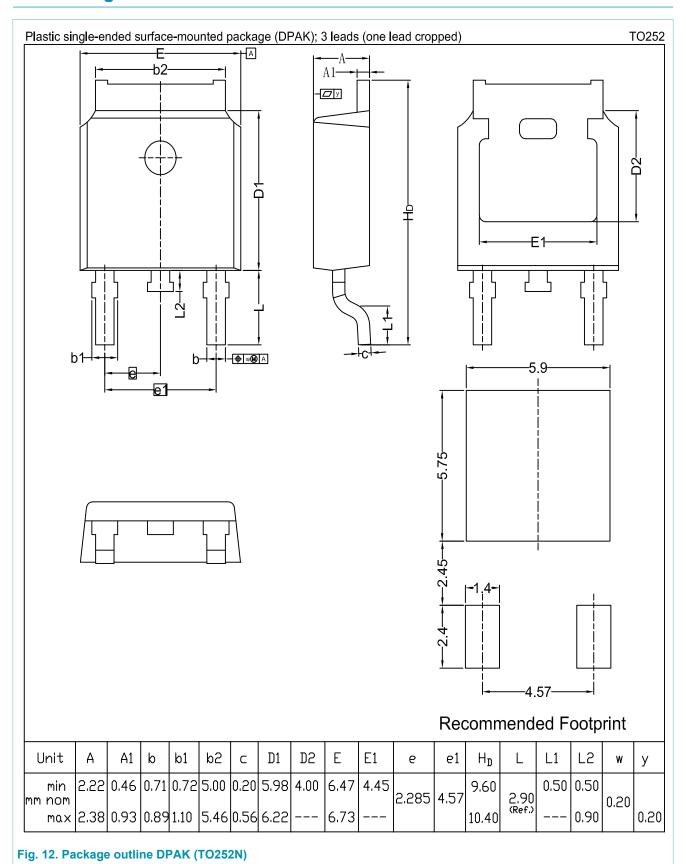


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

10. Package outline



11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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12. Contents

1.	General description	1
2.	Features and benefits	1
3.	Applications	1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Limiting values	3
8.	Thermal characteristics	6
9.	Characteristics	7
10	. Package outline	9
11	. Legal information	10

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